

**HLMP-3301, HLMP-3401, HLMP-3507, HLMP-3762,  
HLMP-3862, HLMP-3962, HLMP-D401**  
T-1<sup>3/4</sup> (5 mm) Diffused LED Lamps

**AVAGO**  
TECHNOLOGIES

**Data Sheet**



**Description**

This family of T-1<sup>3/4</sup> tinted, diffused LED lamps is widely used in general purpose indicator applications. Diffusants, tints, and optical design are balanced to yield superior light output and wide viewing angles. Several intensity choices are available in each color for increased design flexibility.

**Selection Guide**

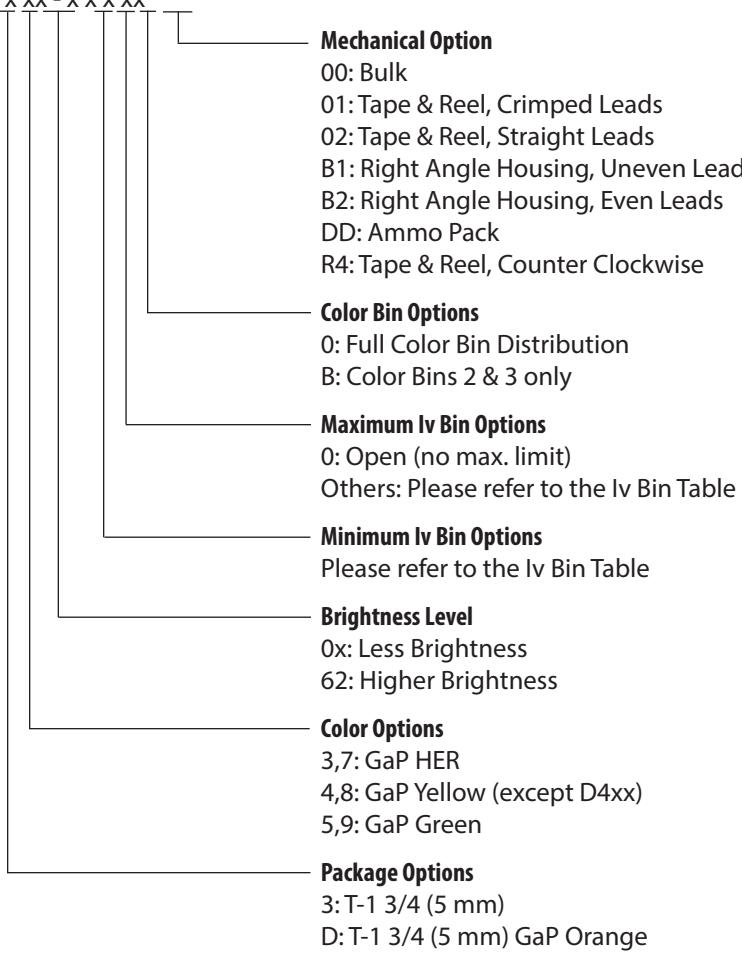
Material/ Color	Part Number	Luminous Intensity I <sub>v</sub> (mcd) at 10 mA	
		Min.	Max.
GaP HER	HLMP-3301	5.4	–
	HLMP-3301-D00xx	2.1	–
	HLMP-3301-F00xx	5.4	–
	HLMP-3301-FG0xx	5.4	17.2
	HLMP-3762	8.6	–
	HLMP-3762-G00xx	8.6	–
GaP Yellow	HLMP-3401	5.7	–
	HLMP-3401-E00xx	5.7	–
	HLMP-3401-EF0xx	5.7	18.4
	HLMP-3862	9.2	–
GaP Orange	HLMP-D401	5.4	–
	HLMP-D401-EF0xx	3.4	10.8
GaP Green	HLMP-3507	4.2	–
	HLMP-3507-D00xx	4.2	–
	HLMP-3507-EF0xx	6.7	21.2
	HLMP-3962	10.6	–
	HLMP-3962-F00xx	10.6	–

**Features**

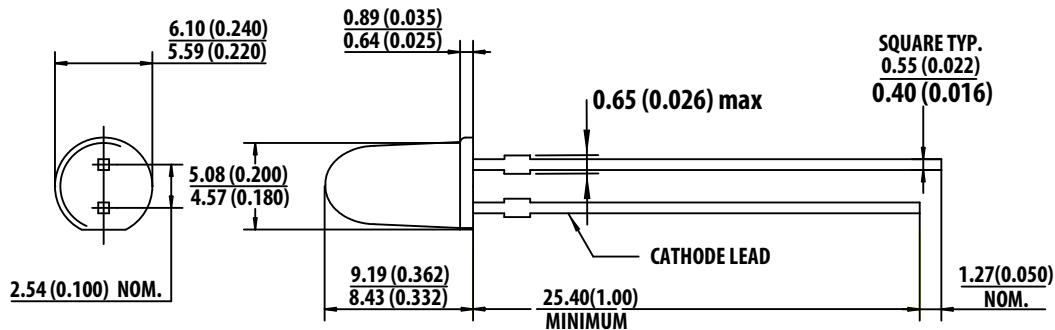
- High intensity
- Choice of 4 bright colors
  - High Efficiency Red
  - Orange
  - Yellow
  - High Performance Green
- Popular T-1<sup>3/4</sup> diameter package
- Selected minimum intensities
- Wide viewing angle
- General purpose leads
- Reliable and rugged
- Available on tape and reel

## Part Numbering System

HLMP - x x xx - x x x xx



## Package Dimensions



## Notes:

1. All dimensions are in mm (inches).
2. An epoxy meniscus may extend about 1 mm (0.040") down the leads.
3. For PCB hole recommendations, see the Precautions section.

## Optical/Electrical Characteristics at $T_A = 25^\circ\text{C}$

Symbol	Parameter	Color	Min.	Typ.	Max.	Units	Test Condition
$2\theta_{1/2}$	Included Angle Between Half Luminous Intensity Points	High Efficiency Red Orange Yellow Green	60 60 60 60	60		Deg.	$I_F = 10 \text{ mA}$ See Note 1
	Peak Wavelength	High Efficiency Red Orange Yellow Green		635 600 583 565		nm	Measurement at Peak
	Spectral Line Halfwidth	HER/Orange Yellow Green		40 36 28		nm	
	Dominant Wavelength	High Efficiency Red Orange Yellow Green		626 602 585 569		nm	See Note 2
$\tau_s$	Speed of Response	High Efficiency Red Orange Yellow Green		90 280 90 500		ns	
	Capacitance	High Efficiency Red Orange Yellow Green		11 4 15 18		pF	$V_F = 0;$ $f = 1 \text{ MHz}$
$R_{\theta\text{J-PIN}}$	Thermal Resistance	All		260		°C/W	Junction to Cathode Lead
Forward Voltage	HER/Orange Yellow Green		1.9 2.0 2.1	2.4 2.4 2.7	V	$I_F = 10 \text{ mA}$	
$V_R$	Reverse Breakdown Voltage	All	5.0			V	$I_R = 100 \mu\text{A}$
$\eta_V$	Luminous Efficacy	High Efficiency Red Orange Yellow Green	–	145 380 500 595		lumens Watt	See Note 3

### Notes:

1.  $\theta_{1/2}$  is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
2. The dominant wavelength,  $\lambda_d$ , is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
3. Radian intensity,  $I_e$ , in Watts/steradian, may be found from the equation  $I_e = I_v/\eta_V$ , where  $I_v$  is the luminous intensity in candelas and  $\eta_V$  is the luminous efficacy in lumens/Watt.

## Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

Parameter	HER/Orange	Yellow	Green/ Emerald Green	Units
Peak Forward Current	90	60	90	mA
Average Forward Current <sup>[1]</sup>	25	20	25	mA
DC Current <sup>[2]</sup>	30	20	30	mA
Power Dissipation <sup>[3]</sup>	135	85	135	mW
Reverse Voltage ( $I_R = 100 \mu\text{A}$ )	5	5	5	V
Transient Forward Current <sup>[4]</sup> (10 $\mu\text{sec}$ Pulse)	500	500	500	mA
LED Junction Temperature	110	110	110	$^\circ\text{C}$
Operating Temperature Range	-40 to +100	-40 to +100	-20 to +100	$^\circ\text{C}$
Storage Temperature Range	-40 to +100	-40 to +100	-40 to +100	$^\circ\text{C}$

### Notes:

1. See Figure 5 (Red/Orange), 10 (Yellow), or 15 (Green) to establish pulsed operating conditions.
2. For Red, Orange and Green series derate linearly from  $50^\circ\text{C}$  at  $0.5 \text{ mA}/^\circ\text{C}$ . For Yellow series derate linearly from  $50^\circ\text{C}$  at  $0.2 \text{ mA}/^\circ\text{C}$ .
3.  $1.8 \text{ mW}/^\circ\text{C}$ . For Yellow series derate power linearly from  $50^\circ\text{C}$  at  $1.6 \text{ mW}/^\circ\text{C}$ .
4. The transient peak current is the maximum non-recurring peak current that can be applied to the device without damaging the LED die and wirebond. It is not recommended that the device be operated at peak currents beyond the peak forward current listed in the Absolute Maximum Ratings.

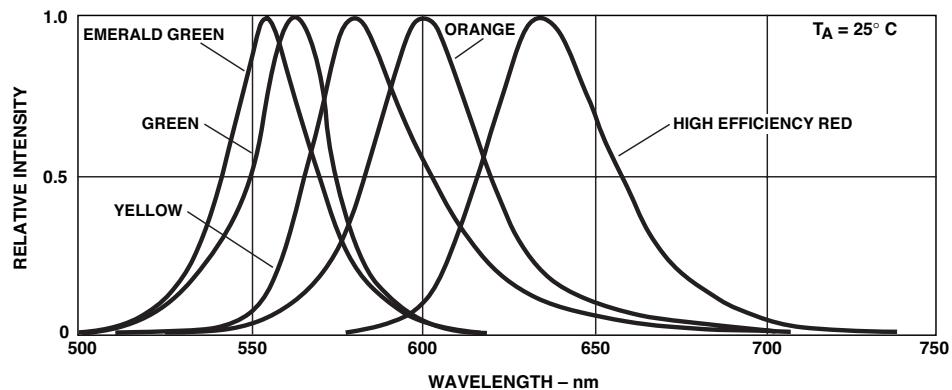


Figure 1. Relative intensity vs. wavelength

## T-1<sup>3/4</sup> High Efficiency Red, Orange Diffused Lamps

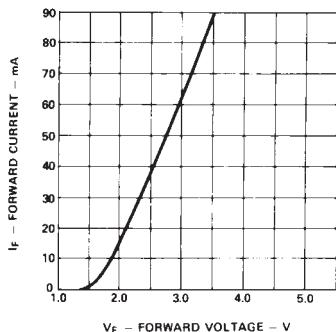


Figure 2. Forward current vs. forward voltage characteristics

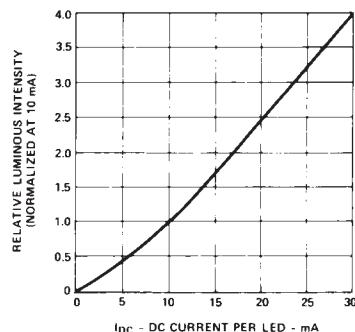


Figure 3. Relative luminous intensity vs. DC forward current

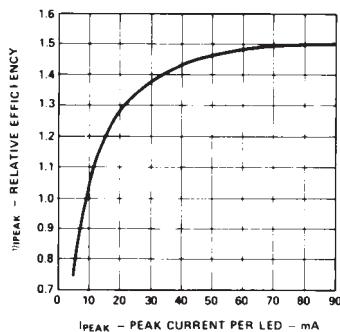


Figure 4. Relative efficiency (luminous intensity per unit current) vs. peak LED current

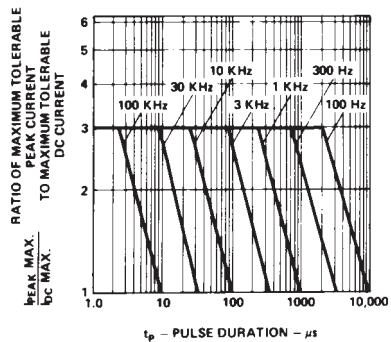


Figure 5. Maximum tolerable peak current vs. pulse duration. ( $I_{DC\ MAX}$  as per MAX ratings)

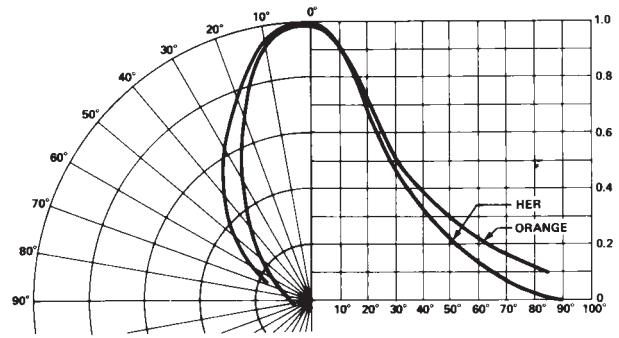


Figure 6. Relative luminous intensity vs. angular displacement

## T-1<sup>3</sup>/4 Yellow Diffused Lamps

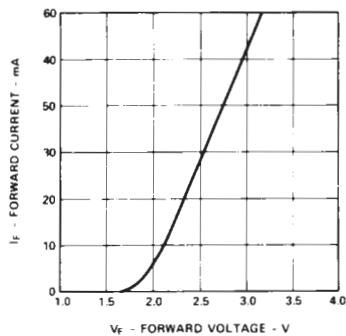


Figure 7. Forward current vs. forward voltage characteristics

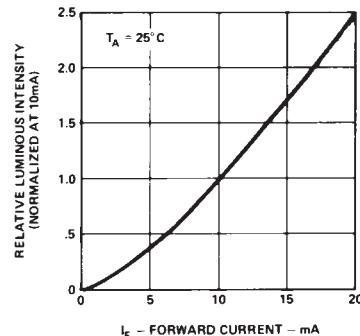


Figure 8. Relative luminous intensity vs. forward current

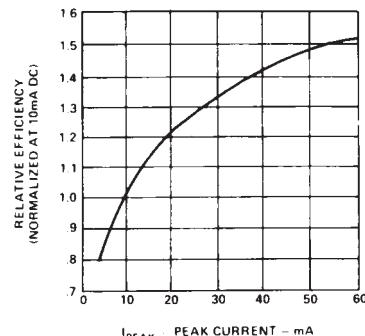


Figure 9. Relative efficiency (luminous intensity per unit current) vs. peak current

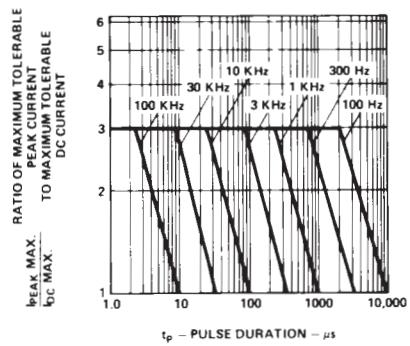


Figure 10. Maximum tolerable peak current vs. pulse duration. ( $I_{DC\ MAX}$  as per MAX ratings)

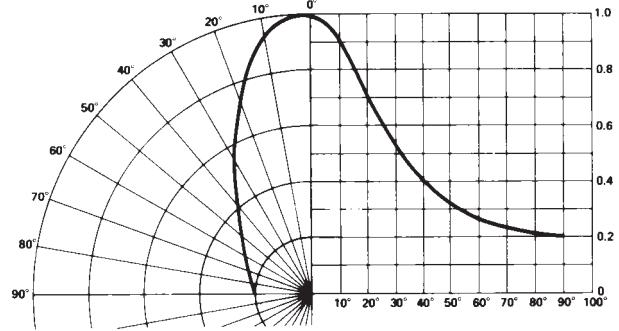


Figure 11. Relative luminous intensity vs. angular displacement

## T-1<sup>3</sup>/4 Green/Emerald Green Diffused Lamps

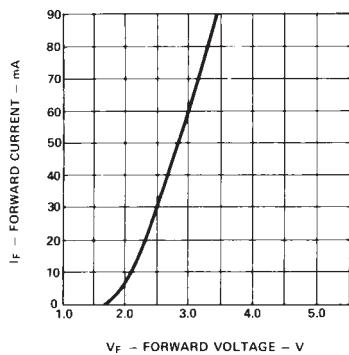


Figure 12. Forward current vs. forward voltage characteristics

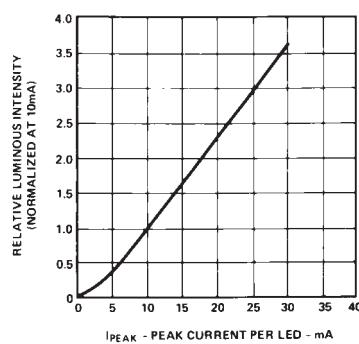


Figure 13. Relative luminous intensity vs. DC forward current

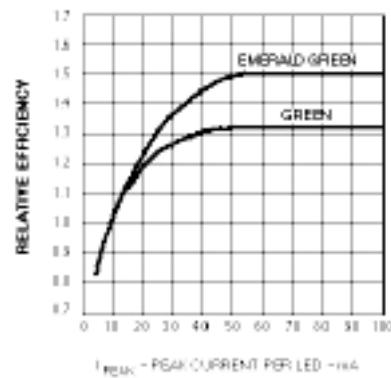


Figure 14. Relative efficiency (luminous intensity per unit current) vs. peak LED current

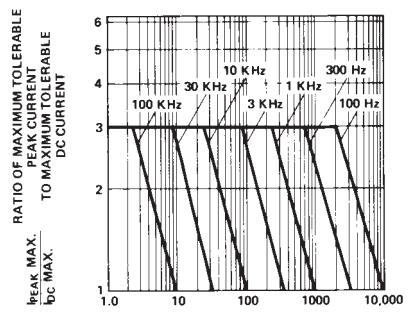


Figure 15. Maximum tolerable peak current vs. pulse duration. ( $I_{Dc\ MAX}$  as per MAX ratings)

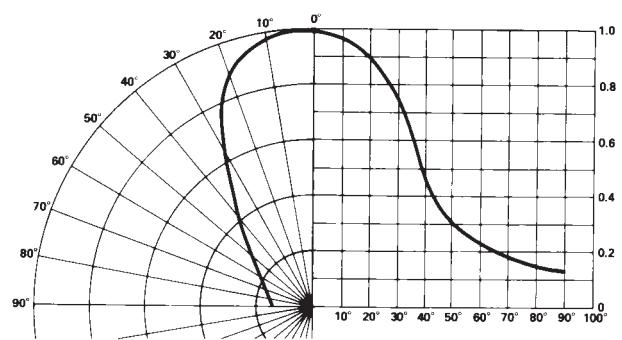


Figure 16. Relative luminous intensity vs. angular displacement

## Intensity Bin Limits

Color	Bin	Intensity Range (mcd)	
		Min.	Max.
Red/Orange	D	2.4	3.8
	E	3.8	6.1
	F	6.1	9.7
	G	9.7	15.5
	H	15.5	24.8
	I	24.8	39.6
	J	39.6	63.4
	K	63.4	101.5
	L	101.5	162.4
	M	162.4	234.6
	N	234.6	340.0
	O	340.0	540.0
	P	540.0	850.0
	Q	850.0	1200.0
	R	1200.0	1700.0
	S	1700.0	2400.0
	T	2400.0	3400.0
	U	3400.0	4900.0
	V	4900.0	7100.0
	W	7100.0	10200.0
	X	10200.0	14800.0
	Y	14800.0	21400.0
	Z	21400.0	30900.0
Yellow	E	6.5	10.3
	F	10.3	16.6
	G	16.6	26.5
	H	26.5	42.3
	I	42.3	67.7
	J	67.7	108.2
	K	108.2	173.2
	L	173.2	250.0
	M	250.0	360.0
	N	360.0	510.0
	O	510.0	800.0
	P	800.0	1250.0
	Q	1250.0	1800.0
	R	1800.0	2900.0
	S	2900.0	4700.0
	T	4700.0	7200.0
	U	7200.0	11700.0
	V	11700.0	18000.0
	W	18000.0	27000.0

## Intensity Bin Limits, continued

Color	Bin	Intensity Range (mcd)	
		Min.	Max.
Green	D	4.7	7.6
	E	7.6	12.0
	F	12.0	19.1
	G	19.1	30.7
	H	30.7	49.1
	I	49.1	78.5
	J	78.5	125.7
	K	125.7	201.1
	L	201.1	289.0
	M	289.0	417.0
	N	417.0	680.0
	O	680.0	1100.0
	P	1100.0	1800.0
	Q	1800.0	2700.0
	R	2700.0	4300.0
	S	4300.0	6800.0
	T	6800.0	10800.0
	U	10800.0	16000.0
	V	16000.0	25000.0
	W	25000.0	40000.0

Maximum tolerance for each bin limit is  $\pm 18\%$ .

## Color Categories

Color	Category #	Lambda (nm)	
		Min.	Max.
Green	6	561.5	564.5
	5	564.5	567.5
	4	567.5	570.5
	3	570.5	573.5
	2	573.5	576.5
Yellow	1	582.0	584.5
	3	584.5	587.0
	2	587.0	589.5
	4	589.5	592.0
	5	592.0	593.0
Orange	1	597.0	599.5
	2	599.5	602.0
	3	602.0	604.5
	4	604.5	607.5
	5	607.5	610.5
	6	610.5	613.5
	7	613.5	616.5
	8	616.5	619.5

Tolerance for each bin limit is  $\pm 0.5$  nm.

## Mechanical Option Matrix

Mechanical Option Code	Definition
00	Bulk Packaging, minimum increment 500 pcs/bag
01	Tape & Reel, crimped leads, minimum increment 1300 pcs/bag
02	Tape & Reel, straight leads, minimum increment 1300 pcs/bag
B1	Right Angle Housing, uneven leads, minimum increment 500 pcs/bag
B2	Right Angle Housing, even leads, minimum increment 500 pcs/bag
DD	Ammo Pack, straight leads with minimum increment 2K/pack
R4	Tape & Reel, straight leads, counter clockwise, anode lead leaving the reel first

**Note:**

All categories are established for classification of products. Products may not be available in all categories. Please contact your local Avago representative for further clarification/information.

## Precautions

### Lead Forming

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering into PC board.
- If lead forming is required before soldering, care must be taken to avoid any excessive mechanical stress induced to LED package. Otherwise, cut the leads of LED to length after soldering process at room temperature. The solder joint formed will absorb the mechanical stress of the lead cutting from traveling to the LED chip die attach and wirebond.
- It is recommended that tooling made to precisely form and cut the leads to length rather than rely upon hand operation.

### Soldering Conditions

- Care must be taken during PCB assembly and soldering process to prevent damage to LED component.
- The closest LED is allowed to solder on board is 1.59 mm below the body (encapsulant epoxy) for those parts without standoff.
- Recommended soldering conditions:

	Manual Solder	
	Wave Soldering	Dipping
Pre-heat Temperature	105 °C Max.	–
Pre-heat Time	30 sec Max.	–
Peak Temperature	250 °C Max.	260 °C Max.
Dwell Time	3 sec Max.	5 sec Max.

- Wave soldering parameter must be set and maintained according to recommended temperature and dwell time in the solder wave. Customer is advised to periodically check on the soldering profile to ensure the soldering profile used is always conforming to recommended soldering condition.
- If necessary, use fixture to hold the LED component in proper orientation with respect to the PCB during soldering process.
- Proper handling is imperative to avoid excessive thermal stresses to LED components when heated. Therefore, the soldered PCB must be allowed to cool to room temperature, 25°C, before handling.
- Special attention must be given to board fabrication, solder masking, surface plating and lead holes size and component orientation to assure solderability.
- Recommended PC board plated through hole sizes for LED component leads:

	LED Component Lead Size	Diagonal	Plated Through-Hole Diameter
Lead size (typ.)	0.45 x 0.45 mm (0.018 x 0.018 in.)	0.636 mm (0.025 in)	0.98 to 1.08 mm (0.039 to 0.043 in)
Dambar shear-off area (max.)	0.65 mm (0.026 in)	0.919 mm (0.036 in)	
Lead size (typ.)	0.50 x 0.50 mm (0.020 x 0.020 in.)	0.707 mm (0.028 in)	1.05 to 1.15 mm (0.041 to 0.045 in)
Dambar shear-off area (max.)	0.70 mm (0.028 in)	0.99 mm (0.039 in)	

**Note:** Refer to application note AN1027 for more information on soldering LED components.

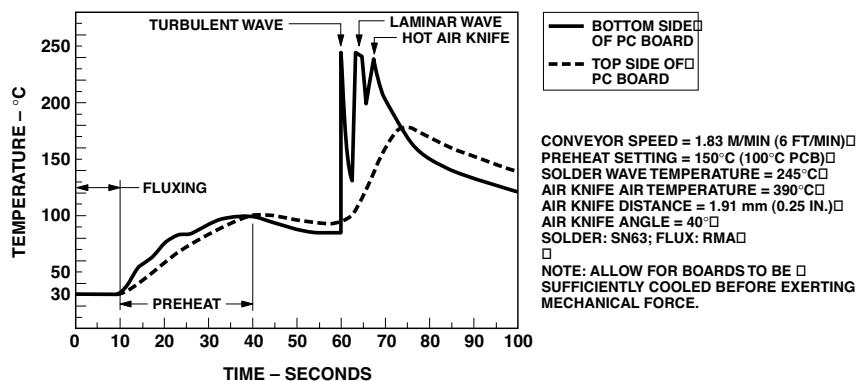


Figure 17. Recommended wave soldering profile

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